

Surface Mount Type

SVT series



OS-CON

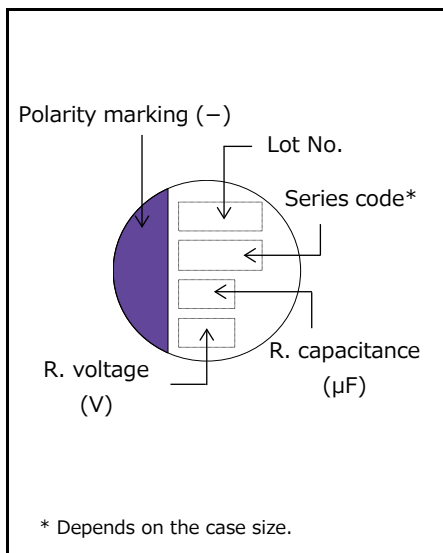
Features

- Low ESR (10 mΩ max.)
- Large capacitance (2700 μF max.)
- 125 °C 2000 h
- RoHS compliance, Halogen free

Specifications

Size code	C65	E7	E12	F12
Category temp. range	-55 °C to +125 °C			
Rated voltage range	2.5 V to 16 V		2.5 V to 50 V	
Nominal cap. range	100 μF to 680 μF	18 μF to 680 μF	39 μF to 1500 μF	68 μF to 2700 μF
Capacitance tolerance	±20 % (120 Hz / +20 °C)			
DC leakage current	Please see the attached characteristics list			
Dissipation factor (tan δ)	Please see the attached characteristics list			
Endurance	+125 °C 2000 h, rated voltage applied			
	Capacitance change	Within ±20 % of the initial value		
	Dissipation factor (tanδ)	≤ 200 % of the initial limit		
	DC leakage current	Within the initial limit		
Damp heat (Steady state)	+60 °C, 90 % to 95 %, 1000 h, No-applied voltage			
	Capacitance change	Within ±20 % of the initial value		
	Dissipation factor (tanδ)	≤ 150 % of the initial limit		
	DC leakage current	Within the initial limit (after voltage processing)		

Marking



Dimensions (not to scale)

Size code	Unit : mm						
	φD±0.5	L ^{+0.1} _{-0.4}	W±0.2	H±0.2	C±0.2	R	P±0.2
C65	6.3	6.4	6.6	6.6	7.3	0.6~0.8	2.1
E7	8.0	6.9	8.3	8.3	9.0	0.6~0.8	3.2
E12	8.0	11.9	8.3	8.3	9.0	0.8~1.1	3.2
F12	10.0	12.6	10.3	10.3	11.0	0.8~1.1	4.6

Characteristics list

Rated voltage (V)	Rated capacitance ($\pm 20\%$) (μF)	Case size (mm)		Size code	Specifications					Standard (Reel size : $\phi 380$)	
		ϕD	L		Ripple current ^{*1} (mA rms)	Allowable ripple current ^{*1} (mA rms)	ESR ^{*2} ($\text{m}\Omega$ max.)	$\tan \delta$ ^{*3}	LC ^{*4} (μA)	Part number	Min. Packaging Q'ty (pcs)
2.5	560	6.3	6.4	C65	1100	3500	16	0.12	300	2R5SVT560M	1000
		6.3	6.4		1000	3500	16	0.12	850	2R5SVT680MX	1000
	680	8.0	6.9	E7	1060	3370	20	0.12	500	2R5SVT680M	1000
		8.0	11.9	E12	1620	5150	10	0.12	750	2R5SVT1500M	400
		10.0	12.6	F12	1600	5070	12	0.12	1350	2R5SVT2700M	400
4.0	560	8.0	6.9	E7	1010	3220	22	0.12	500	4SVT560M	1000
	1500	8.0	11.9	E12	1480	4700	12	0.12	1200	4SVT1500M	400
6.3	330	6.3	6.4	C65	1070	3390	15	0.12	415	6SVT330M	1000
	390	8.0	6.9	E7	1010	3220	22	0.12	491	6SVT390M	1000
	820	8.0	11.9	E12	1480	4700	12	0.12	1033	6SVT820M	400
16	100	6.3	6.4	C65	780	2490	24	0.12	300	16SVT100M	1000
	270	8.0	6.9	E7	1040	3300	22	0.12	864	16SVT270M	1000
	560	8.0	11.9	E12	1560	4950	14	0.12	1792	16SVT560M	400
	1000	10.0	12.6	F12	1700	5400	12	0.12	3200	16SVT1000M	400
20	180	8.0	6.9	E7	1010	3200	25	0.12	720	20SVT180M	1000
	390	8.0	11.9	E12	1560	4950	14	0.12	1560	20SVT390M	400
	560	10.0	12.6	F12	1700	5400	12	0.12	2240	20SVT560M	400
25	100	8.0	6.9	E7	1010	3200	24	0.12	500	25SVT100M	1000
	180	8.0	11.9	E12	1470	4650	16	0.12	900	25SVT180M	400
	330	10.0	12.6	F12	1580	5000	14	0.12	1650	25SVT330M	400
35	39	8.0	6.9	E7	880	2800	30	0.12	273	35SVT39M	1000
	82	8.0	11.9	E12	1260	4000	20	0.12	574	35SVT82M	400
	120	10.0	12.6	F12	1390	4400	18	0.12	840	35SVT120M	400
50	18	8.0	6.9	E7	850	2700	35	0.12	180	50SVT18M	1000
	39	8.0	11.9	E12	1200	3800	25	0.12	390	50SVT39M	400
	68	10.0	12.6	F12	1350	4300	20	0.12	680	50SVT68M	400

*1: Ripple current (100 kHz / $+105\text{ }^\circ\text{C} < \text{Tx} \leq +125\text{ }^\circ\text{C}$) / Allowable ripple current (100 kHz / $\text{Tx} \leq +105\text{ }^\circ\text{C}$)

Tx: Temperature measured at the top surface of aluminum case including self-heating by ripple current

*2: ESR (100 kHz to 300 kHz / $+20\text{ }^\circ\text{C}$)

*3: $\tan \delta$ (120 Hz / $+20\text{ }^\circ\text{C}$)

*4: After 2 minutes

◆ Please refer to each page in this catalog for "Reflow conditions" and "Taping specifications".

Frequency correction factor for ripple current

Frequency(f)	$120\text{ Hz} \leq f < 1\text{ kHz}$	$1\text{ kHz} \leq f < 10\text{ kHz}$	$10\text{ kHz} \leq f < 100\text{ kHz}$	$100\text{ kHz} \leq f < 500\text{ kHz}$
Coefficient	0.05	0.3	0.7	1

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- When you use the inventory of our products for which it is unclear whether those products are compliant with the RoHS Directive/REACH Regulation, please select "Sales Inquiry" in the website inquiry form and contact us.

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Notices

■ Applicable laws and regulations

- This product complies with the RoHS Directive (Restriction of the use of certain hazardous substances in electrical and electronic equipment (DIRECTIVE 2011/65/EU and (EU)2015/863)).
- No Ozone Depleting Chemicals(ODC's), controlled under the Montreal Protocol Agreement, are used in producing this product.
We do not use PBBs or PBDEs as brominated flame retardants.
- Export procedure which followed export related regulations, such as foreign exchange and a foreign trade method, on the occasion of export of this product.
- These products are not dangerous goods on the transportation as identified by UN(United Nations) numbers or UN classification.

■ Limited applications

- This capacitor is designed to be used for electronics circuits such as audio/visual equipment, home appliances, computers and other office equipment, optical equipment, measuring equipment.
- High reliability and safety are required [be / a possibility that incorrect operation of this product may do harm to a human life or property] more. When use is considered by the use, the delivery specifications which suited the use separately need to be exchanged.

■ Intellectual property rights and licenses

- The technical information in this specification provides examples of our products' typical operations and application circuits. We do not guarantee the non-infringement of third party's intellectual property rights and we do not grant any license, right, or interest in our intellectual property.

Items to be observed

■ For specification

- This specification guarantees the quality and performance of the product as individual components. The durability differs depending on the environment and the conditions of usage. Before use, check and evaluate their compatibility with actual conditions when installed in the products. When safety requirements cannot be satisfied in your technical examination, inform us immediately.
- Do not use the products beyond the specifications described in this document.

■ Upon application to products where safety is regarded as important

Install the following systems for a failsafe design to ensure safety if these products are to be used in equipment where a defect in these products may cause the loss of human life or other signification damage, such as damage to vehicles (automobile, train, vessel), traffic lights, medical equipment, aerospace equipment, electric heating appliances, combustion/ gas equipment, rotating rotating equipment, and disaster/crime prevention equipment.

- (1) The system is equipped with a protection circuit and protection device.
- (2) The system is equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault.

■ Conditions of use

- Before using the products, carefully check the effects on their quality and performance, and determined whether or not they can be used. These products are designed and manufactured for general-purpose and standard use in general electronic equipment. These products are not intended for use in the following special conditions.
 - (1) In liquid, such as Water, Oil, Chemicals, or Organic solvent.
 - (2) In direct sunlight, outdoors, or in dust.
 - (3) In vapor, such as dew condensation water of resistive element, or water leakage, salty air, or air with a high concentration corrosive gas, such as Cl₂, H₂S, NH₃, SO₂, or NO_x.
 - (4) In an environment where strong static electricity or electromagnetic waves exist.
 - (5) Mounting or placing heat-generating components or inflammables, such as vinyl-coated wires, near these products.
 - (6) Sealing or coating of these products or a printed circuit board on which these products are mounted, with resin and other material.
 - (7) Using solvent, water or water-soluble cleaner for flux cleaning agent after soldering. (In particular, when using water or a water-soluble cleaning agent, be careful not to leave water residues)
 - (8) Using in the atmosphere where strays acid or alkaline.
 - (9) Using in the atmosphere where there are excessive vibration and shock.
 - (10) Using in the atmosphere where there are low pressure or decompression.
- Please arrange circuit design for preventing impulse or transitional voltage. Do not apply voltage, which exceeds the full rated voltage when the capacitors receive impulse voltage, instantaneous high voltage, high pulse voltage etc.
- Our products there is a product are using an electrolyte solution. Therefore, misuse can result in rapid deterioration of characteristics and functions of each product. Electrolyte leakage damages printed circuit and affects performance, characteristics, and functions of customer system.

! Guidelines and precautions (OS-CON)**1. Circuit design****1.1 Prohibited circuits**

- (1) Leakage current of the OS-CON may increase in the following conditions.
 - (a) Soldering
 - (b) When voltage is not applied : high temperature no-load test, high temperature and high humidity no-load test, rapidly changing temperature test, etc.
 - (2) Avoid the use of the OS-CON in the following type of circuits because leakage current may increase.
 - (a) High-impedance circuits
 - (b) Coupling circuits
 - (c) Time constant circuits
 - (d) Other circuits that are significantly affected by leakage current.
- * If you plan to use 2 or more OS-CONs in a series connection, please contact us before use.

1.2 Failure and life-span

The failure rate is 0.5 % /1000 h (Confidence level : 60 %) based on JIS C 5003.

The prospective failure is not zero. The mainly failure modes are as follows.

1.2-1 Contingency failure

The most common failure mode is a short circuit. Mainly caused by the soldering or operating temperature environment, along with heat stresses, electrical stresses or mechanical stresses as follows.

- Applying voltage over the rated voltage.
 - Applying reverse voltage
 - Excessive mechanical stress
 - Applying rush current by sudden charge or discharge out of the specification.
- (1) The following phenomenon is seen when short-current is applied to the OS-CON.
 - (a) When current is relatively low. ($\phi 10$: approx 1 A or less, $\phi 8$: approx 0.5 A or less, $\phi 6.3$: approx 0.2 A or less)

The OS-CON becomes heated, but no effects are visible even when the current is continuously carried.
 - (b) When the short circuit currents exceed the mentioned value above.

After internal temperature increase, sealing rubber may be turned over.
In some cases, odorous gas may be produced.
 - (2) In case a short circuit occurs, ensure safety by fully considering the followings.
 - (a) If odorous gas is released, turn off the main power of the equipment.

In this case, keep your face and hands away from the area.
 - (b) Though it depends on the conditions, it takes seconds to minutes before odorant gas generates.

Protective circuit should operate in this period.
 - (c) If the gas comes into eyes, rinse immediately. If the gas is inhaled, gargle immediately.
 - (d) Do not lick the electrolyte. If the electrolyte touches skin, wash it off with soap immediately.
 - (e) The OS-CON contains combustible substances. In case a large current continues to flow after a short circuit, in the worst case, the shorted-out section may ignite. For safety, install a redundant circuit or a protective circuit, etc.

1.2-2 Wear-out failure (life time)

When lifetime span exceeded the specified guarantee time of endurance and damp heat, electrolyte might insulate and cause electric characteristic changed. This is called an open circuit.

The electric characteristics of capacitance and ESR may possibly change within the specified range in specifications even if it is used under the condition of the rated voltage, electric and mechanical performance. Please note it when designing.

1.3 Leakage current

Mechanical stress may cause OS-CON's leakage current increased.

In such a case, leakage current will gradually decrease by applying voltage (within the category voltage and the upper limit of category temperature).

Then, self-healing speed of leakage current is faster when it is near to the upper limit of category temperature and the category voltage.

OS-CON
leakage current restoration characteristics
16 V.DC / 10 μ F (16 V.DC applied)



OS-CON
leakage current restoration characteristics
10 V.DC / 33 μ F (Ambient temperature 65 °C)
(Measured voltage 10 V)



※ To make the recovery of LC values easy to show, samples that LC values have been increased on purpose are used in the test.

1.4 Rapid charge and discharge limitation

Allowance of a large rush current to flow due to rapid charge and discharge may result in short circuit or large leakage current. The protection circuit, to maintain high reliability, is recommended when rush current to flow to the OS-CON is in the following cases.

- (1) Products which 10 times of allowable ripple current is less than 10 A : It is when 10 A or over of rush current is applied.
- (2) Products which 10 times of allowable ripple current is 10 A or over : It is when rush current, which the figure is over 10 times of allowable ripple current, is applied.

2. Mounting

2.1 Soldering with a soldering iron

- (1) When lead terminals for radial lead type must be processed because the lead pitch and the PCB holes do not match, process them without any stresses to the OS-CON before soldering.
- (2) Solder without any excessive stresses to the OS-CON itself.
- (3) When the OS-CON has been soldered once and needs to be removed, remove it after the solder has been completely melted.
- (4) Do not let the tip of the soldering iron touch the OS-CON itself.

2.2 Flow soldering

- (1) Do not apply flow soldering to OS-CON SMD type.
- (2) Do not solder the OS-CON itself by submerging it in melted solder.
- (3) Solder the opposite side that the OS-CON is mounted on.
- (4) Note that flux does not adhere to anywhere expect the lead terminal.
- (5) Note that other components do not fall over and touch the OS-CON when soldering.

2.3 Reflow soldering

- (1) Do not apply reflow soldering to OS-CON Radial Lead type.
- (2) Please contact us for setting VPS conditions.

2.4 Capacitor handling after soldering

Do not subject the OS-CON to excessive stress as follows.

- (1) Do not tilt, bend or twist the OS-CON.
- (2) Do not move the PCB with holding the OS-CON itself.
- (3) Do not hit the OS-CON with objects.
- (4) When stacking PCBs, make sure that the OS-CON does not touch other PCBs or components.

2.5 Circuit board cleaning

Check the following items before washing PC board with these detergents: high quality alcohol-based cleaning fluid such as Pine-a ST-100S, clean thru 750H, 750L, 710M, 750K or Techno Care FRW 14 through 17 or detergents including substitute freon as AK-225AES or IPA.

- (1) Use immersion or ultrasonic waves to clean within 2 minutes.
- (2) The temperature of the cleaning fluid should be less than 60 °C.
- (3) Watch the contamination of the detergent such as conductivity, pH, specific gravity, water content, etc.
- (4) Do not store the OS-CON in a location subject to gases from the cleaning fluid or in an airtight container after cleaning.
- (5) Dry the PCB or OS-CON with hot air that should be less than the upper category temperature.
- (6) Please note that indication may disappear when rubbing print side after washing depending on a cleaner.
- (7) Please contact us for details about detergents, cleaning methods and detergents other than those listed above.

2.6 Fixatives and coating materials

- (1) Select the appropriate covering and sealant materials for the OS-CON. In particular, don't use acetone in the fixative, coating agent and diluent.
- (2) Before applying the fixative or coating, completely remove any flux residue and foreign matter from the area where the board and the OS-CON will be jointed together.
- (3) Allow any detergent to dry before applying the fixative or coating.
- (4) Please contact us for the fixative and coating heat curing conditions.

2.7 Capacitor insulation

Be sure to completely separate the case, negative lead terminal, positive lead terminal and PC board patterns with each other due to the following reasons.

- (1) Insulation is not guaranteed at a part of resin on the surface of a case.
- (2) It offers inconstant resistance between a case and a negative lead terminal and it isn't insulated.

3. Storage

Open the bags just before mounting and use up all products once opened,
For keeping a good solderability, store the OS-CON as follows.

		Before unsealing	After unsealing
SMD type* ¹		Within 24 months after shipment	Within 30 days from opening (packaged with carrier tape)
Radial lead type	Bag packing product	Within 30 months after shipment	Within 7 days from opening
	Taping product	Within 24 months after shipment	

*1 : The JEDEC J-STD-020 standard is not applicable

* Intellectual property right

We, Panasonic Group are providing the product and service that customers can use without anxiety, and are working positively on the protection of our products under intellectual property rights.

Representative patents relating to OS-CON are as follows:

US Patent No.6508846, No.7158367